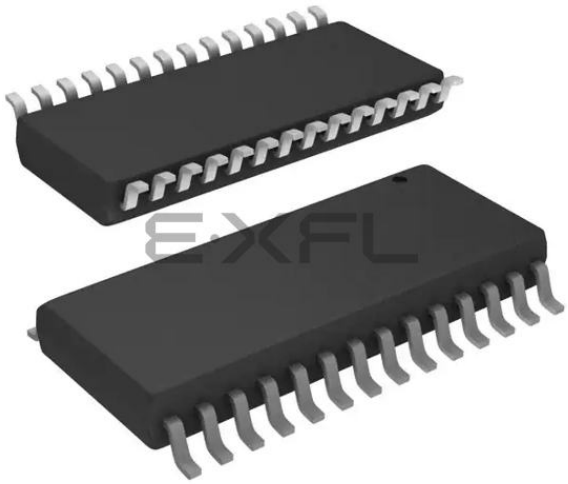

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	32MHz
Connectivity	I²C, IrDA, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	24
Program Memory Size	16KB (5.5K x 24)
Program Memory Type	FLASH
EEPROM Size	512 x 8
RAM Size	1.5K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 9x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24f16ka102t-i-so

2.4 Voltage Regulator Pin (VCAP)

Note: This section applies only to PIC24F K devices with an on-chip voltage regulator.

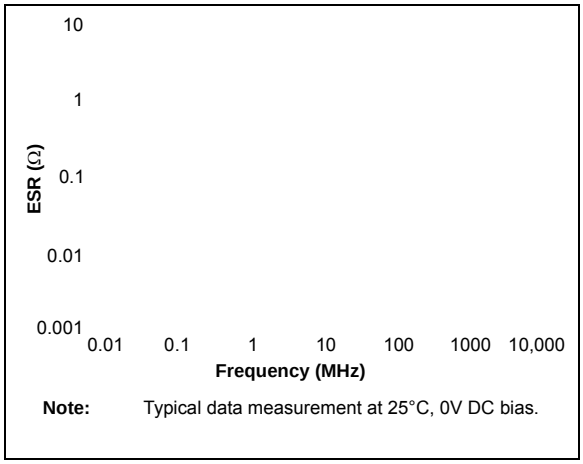
Some of the PIC24F K devices have an internal voltage regulator. These devices have the voltage regulator output brought out on the VCAP pin. On the PIC24F K devices with regulators, a low-ESR (< 5Ω) capacitor is required on the VCAP pin to stabilize the voltage regulator output. The VCAP pin must not be connected to VDD and must use a capacitor of 10 µF connected to ground. The type can be ceramic or tantalum. Suitable examples of capacitors are shown in Table 2-1. Capacitors with equivalent specifications can be used.

Designers may use Figure 2-3 to evaluate ESR equivalence of candidate devices.

The placement of this capacitor should be close to VCAP. It is recommended that the trace length not exceed 0.25 inch (6 mm). Refer to **Section 29.0 "Electrical Characteristics"** for additional information.

Refer to **Section 29.0 "Electrical Characteristics"** for information on VDD and VDDCORE.

FIGURE 2-3: FREQUENCY vs. ESR PERFORMANCE FOR SUGGESTED VCAP



Note: Typical data measurement at 25°C, 0V DC bias.

TABLE 2-1: SUITABLE CAPACITOR EQUIVALENTS

Make	Part #	Nominal Capacitance	Base Tolerance	Rated Voltage	Temp. Range
TDK	C3216X7R1C106K	10 µF	±10%	16V	-55 to 125ºC
TDK	C3216X5R1C106K	10 µF	±10%	16V	-55 to 85ºC
Panasonic	ECJ-3YX1C106K	10 µF	±10%	16V	-55 to 125ºC
Panasonic	ECJ-4YB1C106K	10 µF	±10%	16V	-55 to 85ºC
Murata	GRM32DR71C106KA01L	10 µF	±10%	16V	-55 to 125ºC
Murata	GRM31CR61C106KC31L	10 µF	±10%	16V	-55 to 85ºC

FIGURE 3-2: PROGRAMMER'S MODEL

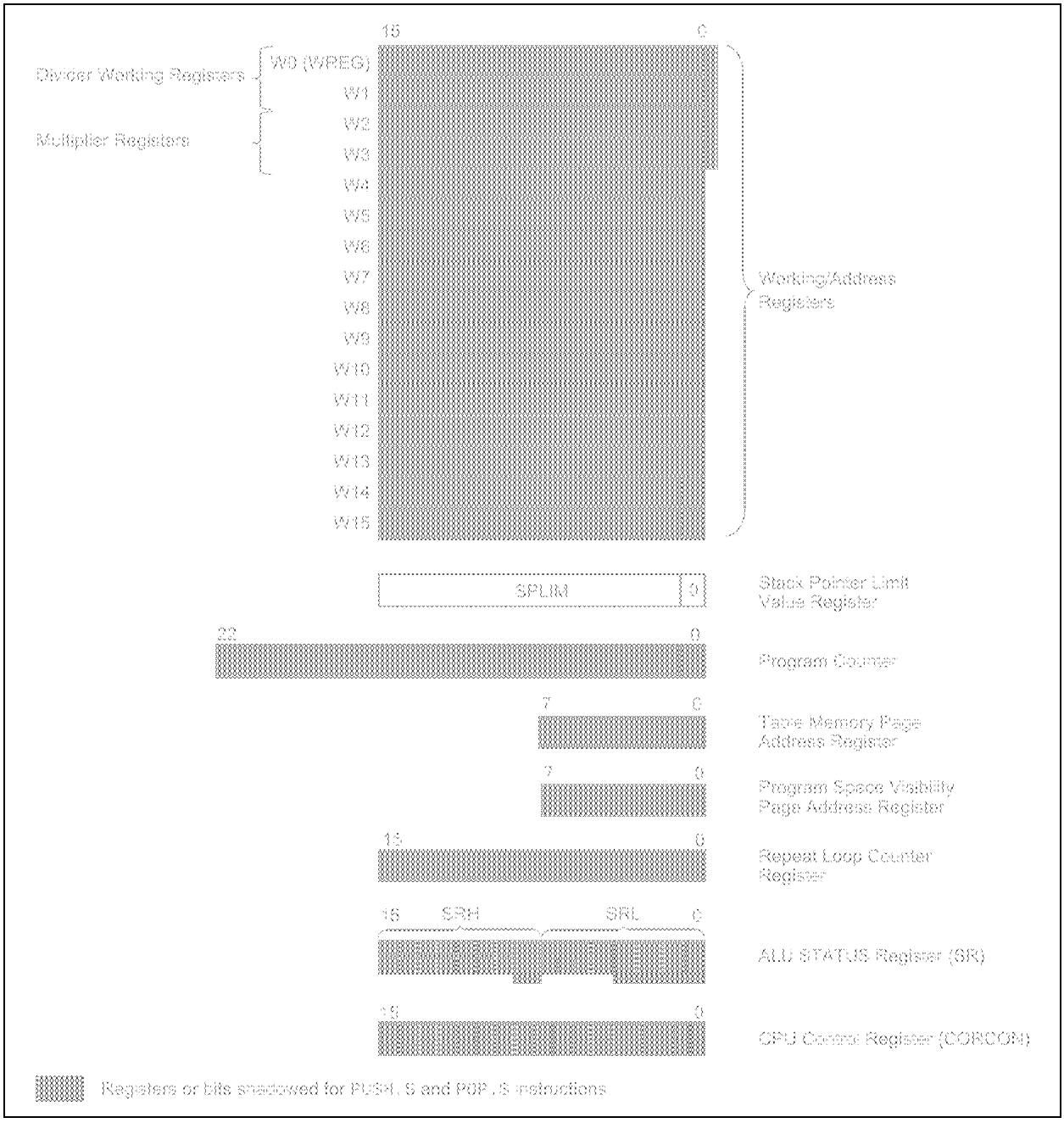


TABLE 4-6: TIMER REGISTER MAP

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TMR1	0100	Timer1 Register																0000
PR1	0102	Timer1 Period Register																FFFF
T1CON	0104	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS1	TCKPS0	—	TSYNC	TCS	—	0000
TMR2	0106	Timer2 Register																0000
TMR3HLD	0108	Timer3 Holding Register (for 32-bit timer operations only)																0000
TMR3	010A	Timer3 Register																0000
PR2	010C	Timer2 Period Register																FFFF
PR3	010E	Timer3 Period Register																FFFF
T2CON	0110	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS1	TCKPS0	T32	—	TCS	—	0000
T3CON	0112	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS1	TCKPS0	—	—	TCS	—	0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-7: INPUT CAPTURE REGISTER MAP

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
IC1BUF	0140	Input Capture 1 Register																FFFF
IC1CON	0142	—	—	ICSIDL	—	—	—	—	—	ICTMR	ICI1	ICI0	ICOV	ICBNE	ICM2	ICM1	ICM0	0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-8: OUTPUT COMPARE REGISTER MAP

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
OC1RS	0180	Output Compare 1 Secondary Register																FFFF
OC1R	0182	Output Compare 1 Register																FFFF
OC1CON	0184	—	—	OCSIDL	—	—	—	—	—	—	—	—	OCFLT	OCTSEL	OCM2	OCM1	OCM0	0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

4.3.2 DATA ACCESS FROM PROGRAM MEMORY AND DATA EEPROM MEMORY USING TABLE INSTRUCTIONS

The TBLRDL and TBLWTL instructions offer a direct method of reading or writing the lower word of any address within the program memory without going through data space. It also offers a direct method of reading or writing a word of any address within data EEPROM memory. The TBLRDH and TBLWTH instructions are the only method to read or write the upper 8 bits of a program space word as data.

Note: The TBLRDH and TBLWTH instructions are not used while accessing data EEPROM memory.

The PC is incremented by 2 for each successive 24-bit program word. This allows program memory addresses to directly map to data space addresses. Program memory can thus be regarded as two 16-bit, word-wide address spaces, residing side by side, each with the same address range. TBLRDL and TBLWTL access the space which contains the least significant data word, and TBLRDH and TBLWTH access the space which contains the upper data byte.

Two table instructions are provided to move byte or word-sized (16-bit) data to and from program space. Both function as either byte or word operations.

1. TBLRDL (Table Read Low): In Word mode, it maps the lower word of the program space location (P<15:0>) to a data address (D<15:0>).

   In Byte mode, either the upper or lower byte of the lower program word is mapped to the lower byte of a data address. The upper byte is selected when byte select is '1'; the lower byte is selected when it is '0'.

2. TBLRDH (Table Read High): In Word mode, it maps the entire upper word of a program address (P<23:16>) to a data address. Note that D<15:8>, the 'phantom' byte, will always be '0'.

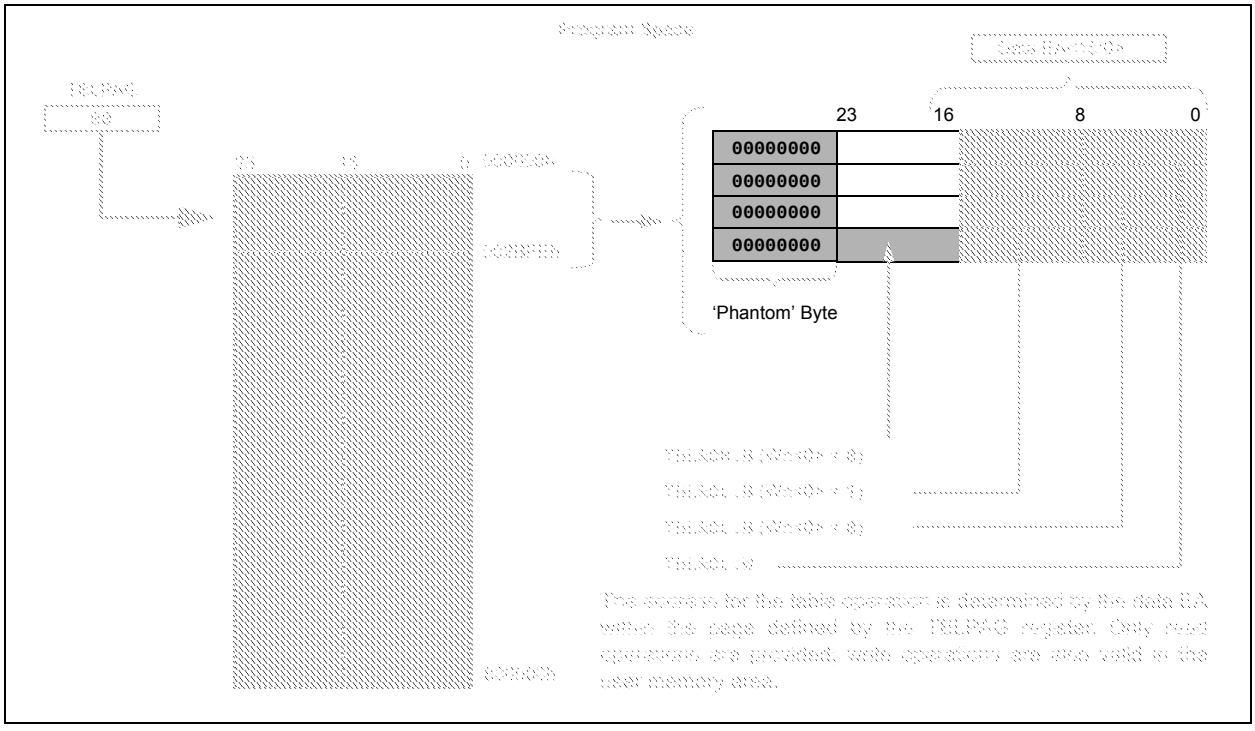
   In Byte mode, it maps the upper or lower byte of the program word to D<7:0> of the data address, as above. Note that the data will always be '0' when the upper 'phantom' byte is selected (byte select = 1).

In a similar fashion, two table instructions, TBLWTH and TBLWTL, are used to write individual bytes or words to a program space address. The details of their operation are explained in **Section 5.0 "Flash Program Memory"**.

For all table operations, the area of program memory space to be accessed is determined by the Table Memory Page Address register (TBLPAG). TBLPAG covers the entire program memory space of the device, including user and configuration spaces. When TBLPAG<7> = 0, the table page is located in the user memory space. When TBLPAG<7> = 1, the page is located in configuration space.

Note: Only table read operations will execute in the configuration memory space, and only then, in implemented areas, such as the Device ID. Table write operations are not allowed.

FIGURE 4-6: ACCESSING PROGRAM MEMORY WITH TABLE INSTRUCTIONS



4.3.3 READING DATA FROM PROGRAM MEMORY USING PROGRAM SPACE VISIBILITY

The upper 32 Kbytes of data space may optionally be mapped into an 8K word page (in PIC24F08KA1XX devices) and a 16K word page (in PIC24F16KA1XX devices) of the program space. This provides transparent access of stored constant data from the data space without the need to use special instructions (i.e., TBLRDL/H).

Program space access through the data space occurs if the MSb of the data space, EA, is '1', and PSV is enabled by setting the PSV bit in the CPU Control (CORCON<2>) register. The location of the program memory space to be mapped into the data space is determined by the Program Space Visibility Page Address register (PSVPAG). This 8-bit register defines any one of 256 possible pages of 16K words in program space. In effect, PSVPAG functions as the upper 8 bits of the program memory address, with the 15 bits of the EA functioning as the lower bits.

By incrementing the PC by 2 for each program memory word, the lower 15 bits of data space addresses directly map to the lower 15 bits in the corresponding program space addresses.

Data reads from this area add an additional cycle to the instruction being executed, since two program memory fetches are required.

Although each data space address, 8000h and higher, maps directly into a corresponding program memory address (see Figure 4-7), only the lower 16 bits of the 24-bit program word are used to contain the data. The upper 8 bits of any program space locations used as data should be programmed with '1111 1111' or '0000 0000' to force a NOP. This prevents possible issues should the area of code ever be accidentally executed.

Note:	PSV access is temporarily disabled during table reads/writes.

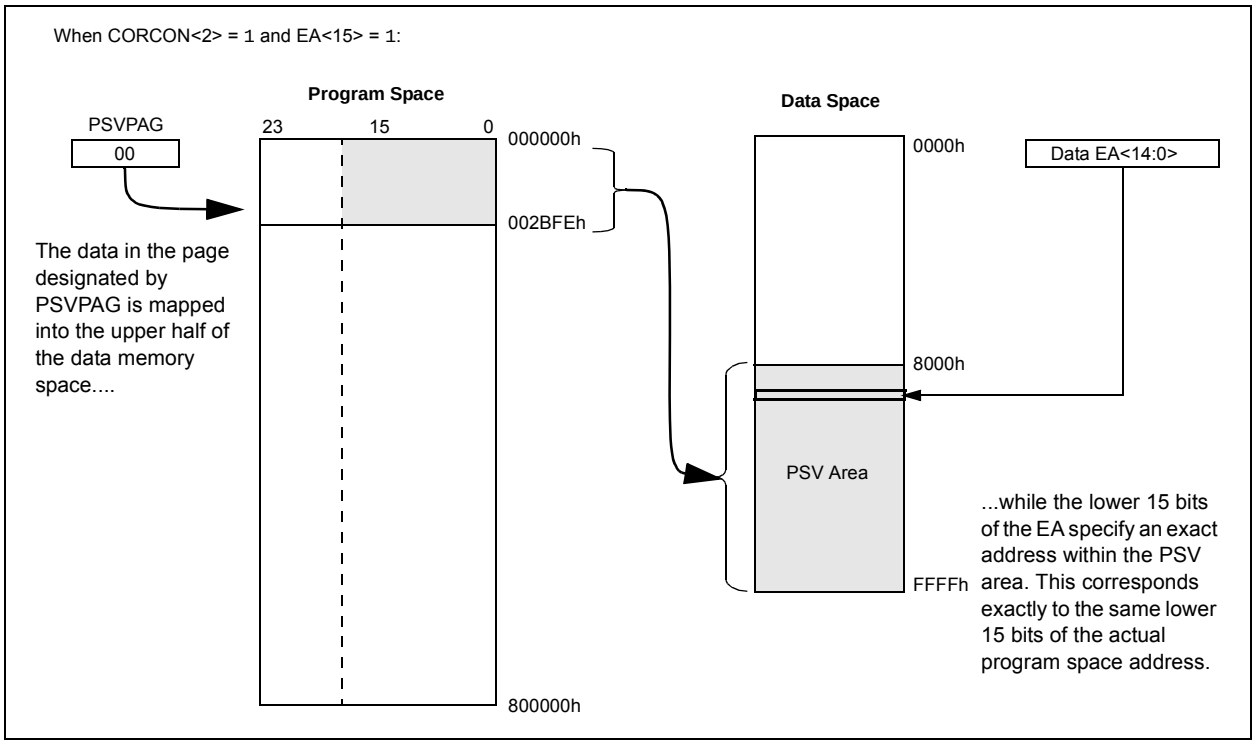
For operations that use PSV and are executed outside a REPEAT loop, the MOV and MOV.D instructions will require one instruction cycle in addition to the specified execution time. All other instructions will require two instruction cycles in addition to the specified execution time.

For operations that use PSV, which are executed inside a REPEAT loop, there will be some instances that require two instruction cycles in addition to the specified execution time of the instruction:

- Execution in the first iteration
- Execution in the last iteration
- Execution prior to exiting the loop due to an interrupt
- Execution upon re-entering the loop after an interrupt is serviced

Any other iteration of the REPEAT loop will allow the instruction accessing data, using PSV, to execute in a single cycle.

FIGURE 4-7: PROGRAM SPACE VISIBILITY OPERATION



5.5.1 PROGRAMMING ALGORITHM FOR FLASH PROGRAM MEMORY

The user can program one row of Flash program memory at a time by erasing the programmable row. The general process is:

1. Read a row of program memory (32 instructions) and store in data RAM.
2. Update the program data in RAM with the desired new data.
3. Erase a row (see Example 5-1):
   a) Set the NVMOP bits (NVMCON<5:0>) to '011000' to configure for row erase. Set the ERASE (NVMCON<6>) and WREN (NVMCON<14>) bits.
   b) Write the starting address of the block to be erased into the TBLPAG and W registers.
   c) Write 55h to NVMKEY.
   d) Write AAh to NVMKEY.
   e) Set the WR bit (NVMCON<15>). The erase cycle begins and the CPU stalls for the duration of the erase cycle. When the erase is done, the WR bit is cleared automatically.
4. Write the first 32 instructions from data RAM into the program memory buffers (see Example 5-1).
5. Write the program block to Flash memory:
   a) Set the NVMOP bits to '000100' to configure for row programming. Clear the ERASE bit and set the WREN bit.
   b) Write 55h to NVMKEY.
   c) Write AAh to NVMKEY.
   d) Set the WR bit. The programming cycle begins and the CPU stalls for the duration of the write cycle. When the write to Flash memory is done, the WR bit is cleared automatically.

For protection against accidental operations, the write initiate sequence for NVMKEY must be used to allow any erase or program operation to proceed. After the programming command has been executed, the user must wait for the programming time until programming is complete. The two instructions following the start of the programming sequence should be NOPs, as displayed in Example 5-5.

EXAMPLE 5-1: ERASING A PROGRAM MEMORY ROW – ASSEMBLY LANGUAGE CODE

```
; Set up NVMCON for row erase operation
        MOV     #0x4058, W0                 ;
        MOV     W0, NVMCON                  ; Initialize NVMCON
; Init pointer to row to be ERASED
        MOV     #tblpage(PROG_ADDR), W0     ;
        MOV     W0, TBLPAG                  ; Initialize PM Page Boundary SFR
        MOV     #tbloffset(PROG_ADDR), W0   ; Initialize in-page EA[15:0] pointer
        TBLWTL  W0, [W0]                    ; Set base address of erase block
        DISI    #5                          ; Block all interrupts
                                              for next 5 instructions
        MOV     #0x55, W0
        MOV     W0, NVMKEY                  ; Write the 55 key
        MOV     #0xAA, W1                   ;
        MOV     W1, NVMKEY                  ; Write the AA key
        BSET    NVMCON, #WR                 ; Start the erase sequence
        NOP                                 ; Insert two NOPs after the erase
        NOP                                 ; command is asserted
```

EXAMPLE 5-2: ERASING A PROGRAM MEMORY ROW – 'C' LANGUAGE CODE

```
// C example using MPLAB C30

int __attribute__ ((space(auto_psv))) progAddr = 0x1234;    // Variable located in Pgm Memory, declared as a
                                                            // global variable
    unsigned int offset;

//Set up pointer to the first memory location to be written

    TBLPAG = __builtin_tblpage(&progAddr);                  // Initialize PM Page Boundary SFR
    offset = __builtin_tbloffset(&progAddr);                // Initialize lower word of address

    __builtin_tblwtl(offset, 0x0000);                       // Set base address of erase block
                                                            // with dummy latch write

    NVMCON = 0x4058;                                        // Initialize NVMCON

    asm("DISI #5");                                         // Block all interrupts for next 5 instructions
    __builtin_write_NVM();                                  // C30 function to perform unlock
                                                            // sequence and set WR
```

7.2.1 POR AND LONG OSCILLATOR START-UP TIMES

The oscillator start-up circuitry and its associated delay timers are not linked to the device Reset delays that occur at power-up. Some crystal circuits (especially low-frequency crystals) will have a relatively long start-up time. Therefore, one or more of the following conditions is possible after $\overline{\text{SYSRST}}$ is released:

- The oscillator circuit has not begun to oscillate.
- The Oscillator Start-up Timer (OST) has not expired (if a crystal oscillator is used).
- The PLL has not achieved a lock (if PLL is used).

The device will not begin to execute code until a valid clock source has been released to the system. Therefore, the oscillator and PLL start-up delays must be considered when the Reset delay time must be known.

7.2.2 FAIL-SAFE CLOCK MONITOR (FSCM) AND DEVICE RESETS

If the FSCM is enabled, it will begin to monitor the system clock source when $\overline{\text{SYSRST}}$ is released. If a valid clock source is not available at this time, the device will automatically switch to the FRC oscillator and the user can switch to the desired crystal oscillator in the Trap Service Routine (TSR).

7.3 Special Function Register Reset States

Most of the Special Function Registers (SFRs) associated with the PIC24F CPU and peripherals are reset to a particular value at a device Reset. The SFRs are grouped by their peripheral or CPU function and their Reset values are specified in each section of this manual.

The Reset value for each SFR does not depend on the type of Reset with the exception of four registers. The Reset value for the Reset Control register, RCON, will depend on the type of device Reset. The Reset value for the Oscillator Control register, OSCCON, will depend on the type of Reset and the programmed values of the FNOSC bits in the Flash Configuration Word (FOSCSEL); see Table 7-2. The RCFGCAL and NVMCON registers are only affected by a POR.

7.4 Deep Sleep BOR (DSBOR)

Deep Sleep BOR is a very low-power BOR circuitry, used when the device is in Deep Sleep mode. Due to low-current consumption, accuracy may vary.

The DSBOR trip point is around 2.0V. DSBOR is enabled by configuring DSBOREN (FDS<6>) = 1. DSBOREN will re-arm the POR to ensure the device will reset if V_{DD} drops below the POR threshold.

7.5 Brown-out Reset (BOR)

The PIC24F16KA102 family devices implement a BOR circuit, which provides the user several configuration and power-saving options. The BOR is controlled by the BORV<1:0> and BOREN<1:0> Configuration bits (FPOR<6:5,1:0>). There are a total of four BOR configurations, which are provided in Table 7-3.

The BOR threshold is set by the BORV<1:0> bits. If BOR is enabled (any values of BOREN<1:0>, except '00'), any drop of V_{DD} below the set threshold point will reset the device. The chip will remain in BOR until V_{DD} rises above threshold.

If the Power-up Timer is enabled, it will be invoked after V_{DD} rises above the threshold. Then, it will keep the chip in Reset for an additional time delay, T_{PWRT}, if V_{DD} drops below the threshold while the Power-up Timer is running. The chip goes back into a BOR and the Power-up Timer will be initialized. Once V_{DD} rises above the threshold, the Power-up Timer will execute the additional time delay.

BOR and the Power-up Timer are independently configured. Enabling the BOR Reset does not automatically enable the PWRT.

7.5.1 SOFTWARE ENABLED BOR

When BOREN<1:0> = 01, the BOR can be enabled or disabled by the user in software. This is done with the control bit, SBOREN (RCON<13>). Setting SBOREN enables the BOR to function as previously described. Clearing the SBOREN disables the BOR entirely. The SBOREN bit operates only in this mode; otherwise, it is read as '0'.

Placing BOR under software control gives the user the additional flexibility of tailoring the application to its environment without having to reprogram the device to change the BOR configuration. It also allows the user to tailor the incremental current that the BOR consumes. While the BOR current is typically very small, it may have some impact in low-power applications.

Note:	Even when the BOR is under software control, the BOR Reset voltage level is still set by the BORV<1:0> Configuration bits; it can not be changed in software.

8.3 Interrupt Control and Status Registers

The PIC24F16KA102 family of devices implements a total of 22 registers for the interrupt controller:

- INTCON1
- INTCON2
- IFS0, IFS1, IFS3 and IFS4
- IEC0, IEC1, IEC3 and IEC4
- IPC0 through IPC5, IPC7 and IPC15 through IPC19
- INTTREG

Global interrupt control functions are controlled from INTCON1 and INTCON2. INTCON1 contains the Interrupt Nesting Disable (NSTDIS) bit, as well as the control and status flags for the processor trap sources. The INTCON2 register controls the external interrupt request signal behavior and the use of the AIV table.

The IFSx registers maintain all of the interrupt request flags. Each source of interrupt has a status bit, which is set by the respective peripherals, or external signal, and is cleared via software.

The IECx registers maintain all of the interrupt enable bits. These control bits are used to individually enable interrupts from the peripherals or external signals.

The IPCx registers are used to set the interrupt priority level for each source of interrupt. Each user interrupt source can be assigned to one of eight priority levels.

The INTTREG register contains the associated interrupt vector number and the new CPU interrupt priority level, which are latched into the Vector Number (VECNUM<6:0>) and the Interrupt Level (ILR<3:0>) bit fields in the INTTREG register. The new interrupt priority level is the priority of the pending interrupt.

The interrupt sources are assigned to the IFSx, IECx and IPCx registers in the same sequence listed in Table 8-2. For example, the INT0 (External Interrupt 0) is depicted as having a vector number and a natural order priority of 0. Thus, the INT0IF status bit is found in IFS0<0>, the INT0IE enable bit in IEC0<0> and the INT0IP<2:0> priority bits in the first position of IPC0 (IPC0<2:0>).

Although they are not specifically part of the interrupt control hardware, two of the CPU control registers contain bits that control interrupt functionality. The ALU STATUS register (SR) contains the IPL<2:0> bits (SR<7:5>). These indicate the current CPU interrupt priority level. The user may change the current CPU priority level by writing to the IPL bits.

The CORCON register contains the IPL3 bit, which together with IPL<2:0>, also indicates the current CPU priority level. IPL3 is a read-only bit so that the trap events cannot be masked by the user's software.

All interrupt registers are described in Register 8-1 through Register 8-21, in the following sections.

REGISTER 8-20: IPC15: INTERRUPT PRIORITY CONTROL REGISTER 15

U-0	U-0	U-0	U-0	U-0	R/W-1	R/W-0	R/W-0
—	—	—	—	—	RTCIP2	RTCIP1	RTCIP0
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-11 **Unimplemented:** Read as ‘0’

bit 10-8 **RTCIP<2:0>:** Real-Time Clock and Calendar Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 7-0 **Unimplemented:** Read as ‘0’

REGISTER 9-1: OSCCON: OSCILLATOR CONTROL REGISTER (CONTINUED)

bit 7 **CLKLOCK:** Clock Selection Lock Enabled bit
If FSCM is enabled (FCKSM1 = 1):
1 = Clock and PLL selections are locked
0 = Clock and PLL selections are not locked and may be modified by setting the OSWEN bit
If FSCM is disabled (FCKSM1 = 0):
Clock and PLL selections are never locked and may be modified by setting the OSWEN bit.

bit 6 **Unimplemented:** Read as '0'

bit 5 **LOCK:** PLL Lock Status bit(2)
1 = PLL module is in lock or PLL module start-up timer is satisfied
0 = PLL module is out of lock, PLL start-up timer is running or PLL is disabled

bit 4 **Unimplemented:** Read as '0'

bit 3 **CF:** Clock Fail Detect bit
1 = FSCM has detected a clock failure
0 = No clock failure has been detected

bit 2 **Unimplemented:** Read as '0'

bit 1 **SOSCEN:** 32 kHz Secondary Oscillator (SOSC) Enable bit
1 = Enable secondary oscillator
0 = Disable secondary oscillator

bit 0 **OSWEN:** Oscillator Switch Enable bit
1 = Initiate an oscillator switch to clock source specified by NOSC<2:0> bits
0 = Oscillator switch is complete

Note 1: Reset values for these bits are determined by the FNOSC Configuration bits.
2: Also resets to '0' during any valid clock switch or whenever a non-PLL Clock mode is selected.

FIGURE 13-2: TIMER2 (16-BIT SYNCHRONOUS) BLOCK DIAGRAM

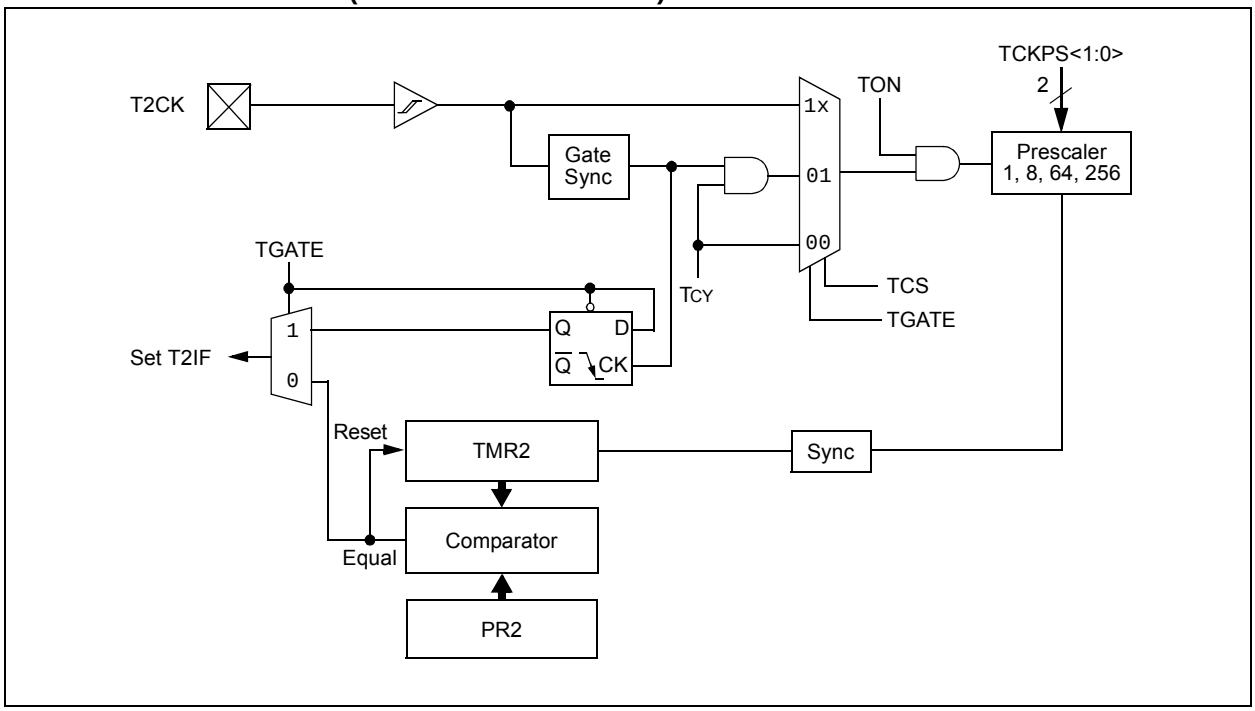
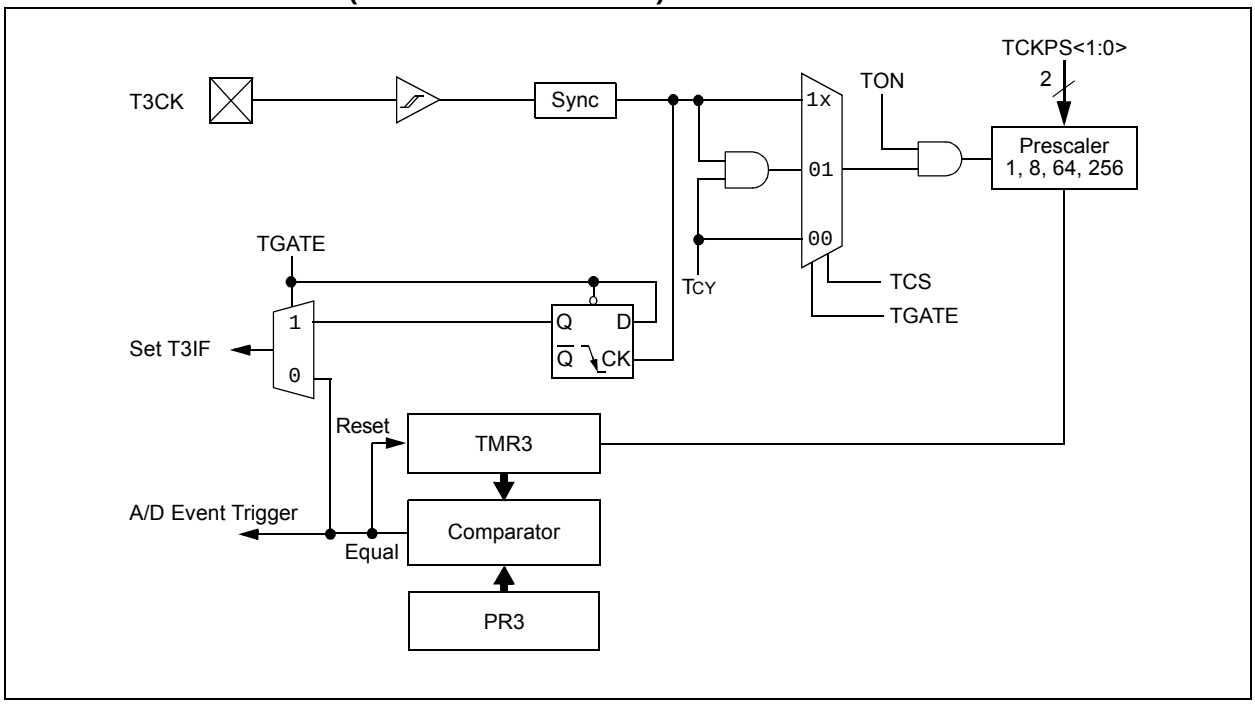


FIGURE 13-3: TIMER3 (16-BIT SYNCHRONOUS) BLOCK DIAGRAM



19.2.5 RTCVAL REGISTER MAPPINGS

REGISTER 19-4: YEAR: YEAR VALUE REGISTER(1)

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
YRTEN3	YRTEN2	YRTEN2	YRTEN1	YRONE3	YRONE2	YRONE1	YRONE0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-8 **Unimplemented:** Read as '0'

bit 7-4 **YRTEN<3:0>:** Binary Coded Decimal Value of Year's Tens Digit bits
Contains a value from 0 to 9.

bit 3-0 **YRONE<3:0>:** Binary Coded Decimal Value of Year's Ones Digit bits
Contains a value from 0 to 9.

Note 1: A write to the YEAR register is only allowed when RTCWREN = 1.

REGISTER 19-5: MTHDY: MONTH AND DAY VALUE REGISTER(1)

U-0	U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	—	MTHTEN0	MTHONE3	MTHONE2	MTHONE1	MTHONE0
bit 15							bit 8

U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	DAYTEN1	DAYTEN0	DAYONE3	DAYONE2	DAYONE1	DAYONE0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as '0'

bit 12 **MTHTEN0:** Binary Coded Decimal Value of Month's Tens Digit bit
Contains a value of '0' or '1'.

bit 11-8 **MTHONE<3:0>:** Binary Coded Decimal Value of Month's Ones Digit bits
Contains a value from 0 to 9.

bit 7-6 **Unimplemented:** Read as '0'

bit 5-4 **DAYTEN<1:0>:** Binary Coded Decimal Value of Day's Tens Digit bits
Contains a value from 0 to 3.

bit 3-0 **DAYONE<3:0>:** Binary Coded Decimal Value of Day's Ones Digit bits
Contains a value from 0 to 9.

Note 1: A write to this register is only allowed when RTCWREN = 1.

REGISTER 23-1: CMxCON: COMPARATOR x CONTROL REGISTERS (CONTINUED)

bit 5 **Unimplemented:** Read as '0'

bit 4 **CREF:** Comparator Reference Select bit (non-inverting input)
1 = Non-inverting input connects to the internal CV_{REF} voltage
0 = Non-inverting input connects to the CxINA pin

bit 3-2 **Unimplemented:** Read as '0'

bit 1-0 **CCH<1:0>:** Comparator Channel Select bits
11 = Inverting input of comparator connects to $V_{BG}/2$
10 = Inverting input of comparator connects to CxIND pin
01 = Inverting input of comparator connects to CxINC pin
00 = Inverting input of comparator connects to CxINB pin

REGISTER 23-2: CMSTAT: COMPARATOR MODULE STATUS REGISTER

R/W-0	U-0	U-0	U-0	U-0	U-0	R-0, HSC	R-0, HSC
CMIDL	—	—	—	—	—	C2EVT	C1EVT
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	R-0, HSC	R-0, HSC
—	—	—	—	—	—	C2OUT	C1OUT
bit 7							bit 0

Legend:	HSC = Hardware Settable/Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **CMIDL:** Comparator Stop in Idle Mode bit
1 = Disable comparator interrupts when the device enters Idle mode; the module is still enabled
0 = Continue operation of all enabled comparators in Idle mode

bit 14-10 **Unimplemented:** Read as '0'

bit 9 **C2EVT:** Comparator 2 Event Status bit (read-only)
Shows the current event status of Comparator 2 (CM2CON<9>).

bit 8 **C1EVT:** Comparator 1 Event Status bit (read-only)
Shows the current event status of Comparator 1 (CM1CON<9>).

bit 7-2 **Unimplemented:** Read as '0'

bit 1 **C2OUT:** Comparator 2 Output Status bit (read-only)
Shows the current output of Comparator 2 (CM2CON<8>).

bit 0 **C1OUT:** Comparator 1 Output Status bit (read-only)
Shows the current output of Comparator 1 (CM1CON<8>).

NOTES:

TABLE 29-6: DC CHARACTERISTICS: OPERATING CURRENT (IDD)

DC CHARACTERISTICS			Standard Operating Conditions: 1.8V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended		
Parameter No.	**Typical(1)**	**Max**	**Units**	**Conditions**	
IDD Current(2)					
DC20	195	330	μA	-40°C	1.8V	0.5 MIPS, FOSC = 1 MHz
DS20a		330		+25°C		
DC20b		330		+60°C		
DC20c		330		+85°C		
DC20d		500		+125°C		
DC20e	365	590	μA	-40°C	3.3V	
DC20f		590		+25°C		
DC20g		645		+60°C		
DC20h		720		+85°C		
DC20i		800		+125°C		
DC22	363	600	μA	-40°C	1.8V	1 MIPS, FOSC = 2 MHz
DC22a		600		+25°C		
DC22b		600		+60°C		
DC22c		600		+85°C		
DC22d		800		+125°C		
DC22e	695	1100	μA	-40°C	3.3V	
DC22f		1100		+25°C		
DC22g		1100		+60°C		
DC22h		1100		+85°C		
DC22i		1500		+125°C		
DC23	11	18	mA	-40°C	3.3V	16 MIPS, FOSC = 32 MHz
DC23a		18		+25°C		
DC23b		18		+60°C		
DC23c		18		+85°C		
DC23d		18		+125°C		
DC27	2.25	3.40	mA	-40°C	2.5V	FRC (4 MIPS), FOSC = 8 MHz
DC27a		3.40		+25°C		
DC27b		3.40		+60°C		
DC27c		3.40		+85°C		
DC27d		3.40		+125°C		
DC27e	3.05	4.60	mA	-40°C	3.3V	
DC27f		4.60		+25°C		
DC27g		4.60		+60°C		
DC27h		4.60		+85°C		
DC27i		5.40		+125°C		

Note 1: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: Operating Parameters:
- EC mode with clock input driven with a square wave rail-to-rail
- I/Os are configured as outputs, driven low
- $\overline{MCLR}$ – VDD
- WDT FSCM is disabled
- SRAM, program and data memory are active
- All PMD bits are set except for modules being measured

TABLE 29-7: DC CHARACTERISTICS: IDLE CURRENT (IIDLE)

DC CHARACTERISTICS			Standard Operating Conditions: 1.8V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Param No.	**Typical(1)**	**Max**	**Units**	**Conditions**		
Idle Current (IIDLE): Core Off, Clock on Base Current, PMD Bits are Set(2)						
DC40	48	100	μA	-40°C	1.8V	0.5 MIPS, FOSC = 1 MHz
DC40a		100		+25°C		
DC40b		100		+60°C		
DC40c		100		+85°C		
DC40d		100		+125°C		
DC40e	106	215	μA	-40°C	3.3V	
DC40f		215		+25°C		
DC40g		215		+60°C		
DC40h		215		+85°C		
DC40i		450		+125°C		
DC42	94	200	μA	-40°C	1.8V	1 MIPS, FOSC = 2 MHz
DC42a		200		+25°C		
DC42b		200		+60°C		
DC42c		200		+85°C		
DC42d		300		+125°C		
DC42e	160	395	μA	-40°C	3.3V	
DC42f		395		+25°C		
DC42g		395		+60°C		
DC42h		395		+85°C		
DC42i		600		+125°C		
DC43	3.1	6.0	mA	-40°C	3.3V	16 MIPS, FOSC = 32 MHz
DC43a		6.0		+25°C		
DC43b		6.0		+60°C		
DC43c		6.0		+85°C		
DC43d		6.0		+125°C		
DC44	0.56	0.74	mA	-40°C	1.8V	FRC (4 MIPS), FOSC = 8 MHz
DC44a		0.74		+25°C		
DC44b		0.74		+60°C		
DC44c		0.74		+85°C		
DC44d		0.74		+125°C		
DC44e	0.95	1.50	mA	-40°C	3.3V	
DC44f		1.50		+25°C		
DC44g		1.50		+60°C		
DC44h		1.50		+85°C		
DC44i		1.50		+125°C		

Note 1: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: Operating Parameters:
- Core is off
- EC mode with the clock input driven with a square wave rail-to-rail
- I/Os are configured as outputs, driven low
- $\overline{MCLR}$ – VDD
- WDT FSCM are disabled
- SRAM, program and data memory are active
- All PMD bits are set except for the modules being measured

TABLE 29-8: DC CHARACTERISTICS: POWER-DOWN CURRENT (IPD) (CONTINUED)

DC CHARACTERISTICS			Standard Operating Conditions: 1.8V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended		
Parameter No.	**Typical(1)**	**Max**	**Units**	**Conditions**	
Power-Down Current (IPD): PMD Bits are Set, PMSLP Bit is '0'(2)					
DC70	0.045	0.200	µA	-40°C, 1.8V	LPBOR(3,4)
DC70a		0.200		+25°C, 1.8V	
DC70b		0.200		+60°C, 1.8V	
DC70c		0.200		+85°C, 1.8V	
DC70d		1.45		+125°C, 1.8V	
DC70e	0.095	0.200	µA	-40°C, 3.3V	
DC70f		0.200		+25°C, 3.3V	
DC70g		0.200		+60°C, 3.3V	
DC70h		0.200		+85°C, 3.3V	
DC70i		1.55		+125°C, 3.3V	
DC71	0.35	0.55	µA	-40°C, 1.8V	Deep Sleep Watchdog Timer: DSWDT (SOSC – LP)(6)
DC71a		0.55		+25°C, 1.8V	
DC71b		0.55		+60°C, 1.8V	
DC71c		0.55		+85°C, 1.8V	
DC71d		1.70		+125°C, 1.8V	
DC71e	0.55	0.75	µA	-40°C, 3.3V	
DC71f		0.75		+25°C, 3.3V	
DC71g		0.75		+60°C, 3.3V	
DC71h		0.75		+85°C, 3.3V	
DC71i		2.10		+125°C, 3.3V	
DC72	0.005	0.200	µA	-40°C, 1.8V	Deep Sleep BOR (DSBOR)(6)
DC72a		0.200		+25°C, 1.8V	
DC72b		0.200		+60°C, 1.8V	
DC72c		0.200		+85°C, 1.8V	
DC72d		0.200		+125°C, 1.8V	
DC72e	0.010	0.200	µA	-40°C, 3.3V	
DC72f		0.200		+25°C, 3.3V	
DC72g		0.200		+60°C, 3.3V	
DC72h		0.200		+85°C, 3.3V	
DC72i		0.200		+125°C, 3.3V	

Note 1: Data in the "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: Base IPD is measured with all peripherals and clocks shut down. All I/Os are configured as outputs and set low. WDT, etc., are all switched off.

3: The Δ current is the additional current consumed when the module is enabled. This current should be added to the base IPD current.

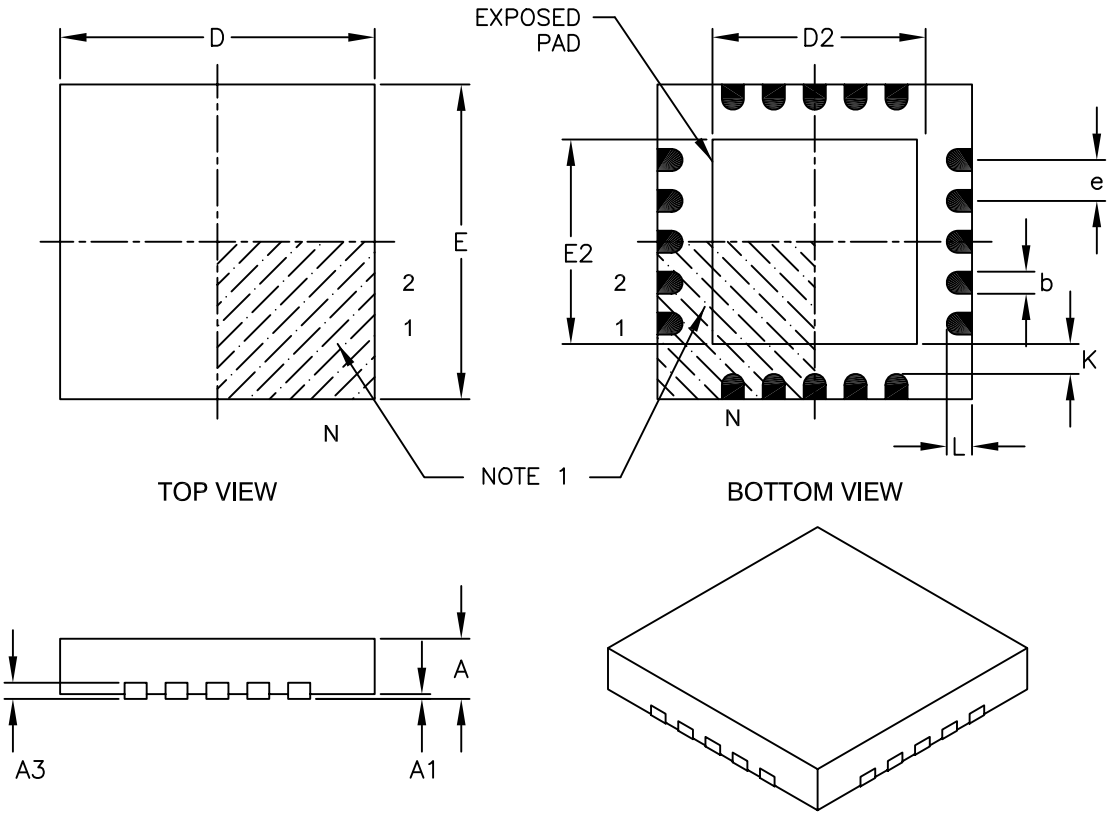
4: Current applies to Sleep only.

5: Current applies to Sleep and Deep Sleep.

6: Current applies to Deep Sleep only.

20-Lead Plastic Quad Flat, No Lead Package (MQ) – 5x5x0.9 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		20	
Pitch	e		0.65 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3		0.20 REF	
Overall Width	E		5.00 BSC	
Exposed Pad Width	E2	3.15	3.25	3.35
Overall Length	D		5.00 BSC	
Exposed Pad Length	D2	3.15	3.25	3.35
Contact Width	b	0.25	0.30	0.35
Contact Length	L	0.35	0.40	0.45
Contact-to-Exposed Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-139B

APPENDIX A: REVISION HISTORY

Revision A (November 2008)

Original data sheet for the PIC24F16KA102 family of devices.

Revision B (March 2009)

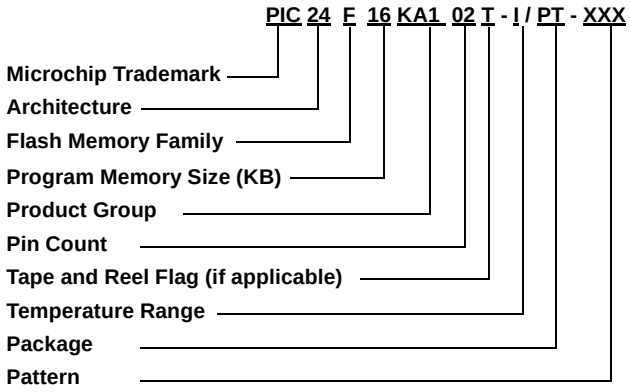
Section 29.0 "Electrical Characteristics" was revised and minor text edits were made throughout the document.

Revision C (October 2011)

- Changed all instances of DSWSRC to DSWAKE.
- Corrected Example 5-2.
- Corrected Example 5-4.
- Corrected Example 6-1.
- Corrected Example 6-3.
- Added a comment to Example 6-5.
- Corrected Figure 9-1 to connect the SOSCI and SOSCO pins to the Schmitt trigger correctly.
- Added register descriptions for PMD1, PMD2, PMD3 and PMD4.
- Added note that RTCC will run in Reset.
- Corrected time values of ADCS (AD1CON3<5:0>).
- Corrected CH0SB and CH0SA (AD1CHS<11:8> and AD1CHS<3:0>) to correctly reference AVDD and AN3.
- Added description of PGCF15 and PGCF14 (AD1PCFG<15:14>).
- Edited Figure 22-2 to correctly reference RIC and the A/D capacitance.
- Changed all references from CTEDG1 to CTED1.
- Changed all references from CTEDG2 to CTED2.
- Changed description of CMIDL: it used to say it disables all comparators in Idle, now only disables interrupts in Idle mode.
- Changed all references of RTCCKSEL to RTCOSC.
- Changed all references of DSLPBOR to DSBOREN.
- Changed all references of DSWCKSEL to DSWDTOSC
- Imported Figure 40-9 from PIC24F FRM, Section 40.
- Added spec for BOR hysteresis.
- Edited Note 1 for Table 29-5 to further describe LPBOR.
- Edited max values of DC20d and DC20e on Table 29-6.
- Edited typical value for DC61-DC61c in Table 29-8.
- Edited Note 2 of Table 29-8.
- Added Note 5 to Table 29-9.
- Added Table 29-15.
- Added AD08 and AD09 in Table 29-26.
- Added Note 3 to Table 29-26.
- Imported Figure 40.10 from PIC24F FRM, Section 40.
- Deleted TVREG spec.
- Imported Figure 15-5 from PIC24F FRM, Section 15.
- Imported Table 15-4 from PIC24F FRM, Section 15.
- Imported Figure 16-22 from PIC24F FRM, Section 16.
- Imported Table 16-9 from PIC24F FRM, Section 16.
- Imported Figure 16-23 from PIC24F FRM, Section 16.
- Imported Table 16-10 from PIC24F FRM, Section 16.
- Imported Figure 21-24 from PIC24F FRM. Section 21.
- Imported Figure 21-25 from PIC24F FRM, Section 21.
- Imported Table 21-5 from PIC24F FRM, Section 21.
- Imported Figure 23-17 from PIC24F FRM, Section 23.
- Imported Table 23-3 from PIC24F FRM, Section 23.
- Imported Figure 23-18 from PIC24F FRM, Section 23.
- Imported Table 23-4 from PIC24F FRM, Section 23.
- Imported Figure 23-19 from PIC24F FRM, Section 23.
- Imported Table 23-5 from PIC24F FRM, Section 23.
- Imported Figure 23-20 from PIC24F FRM, Section 23.
- Imported Table 23-6 from PIC24F FRM, Section 23.
- Imported Figure 24-33 from PIC24F FRM, Section 24.
- Imported Table 24-6 from PIC24F FRM, Section 24.
- Imported Figure 24-34 from PIC24F FRM, Section 24.
- Imported Table 24-7 from PIC24F FRM, Section 24.
- Imported Figure 24-35 from PIC24F FRM, Section 24.
- Imported Table 24-8 from PIC24F FRM, Section 24.
- Imported Figure 24-36 from PIC24F FRM, Section 24.
- Imported Table 24-9 from PIC24F FRM, Section 24.

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.



Architecture	24	= 16-bit modified Harvard without DSP
Flash Memory Family	F	= Flash program memory
Product Group	KA1	= General purpose microcontrollers
Pin Count	01 02	= 20-pin = 28-pin
Temperature Range	I E	= -40°C to +85°C (Industrial) = -40°C to +125°C (Extended)
Package	SP SO SS ML P	= SPDIP = SOIC = SSOP = QFN = PDIP
Pattern	Three-digit QTP, SQTP, Code or Special Requirements (blank otherwise) ES = Engineering Sample	

Examples:

a) PIC24F16KA102-I/ML: General purpose, 16-Kbyte program memory, 28-pin, Industrial temp., QFN package.